

**PATENT ASSIGNMENT**

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Ayako IWASE	05/14/2010
Yuji SAITOU	05/07/2010
Nobuki FURUE	05/10/2010
Shinichi IRIYA	05/24/2010
Hiroyuki OZAWA	05/31/2010
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SONY CORPORATION
<b>Street Address:</b>	1-7-1 Konan, Minato-ku
<b>City:</b>	Tokyo
<b>State/Country:</b>	Japan
<b>Postal Code:</b>	108-0075
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	12793219
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(703)413-2220
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
<b>Phone:</b>	(703) 413-3000
<b>Email:</b>	rlynch@oblon.com
<b>Correspondent Name:</b>	Oblon, Spivak, et al.
<b>Address Line 1:</b>	1940 Duke Street
<b>Address Line 4:</b>	Alexandria, VIRGINIA 22314
<b>ATTORNEY DOCKET NUMBER:</b>	354676US8
<b>NAME OF SUBMITTER:</b>	Ryan P. Lynch

OP \$40.00 12793219

Total Attachments: 4

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**ASSIGNMENT**

WHEREAS, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in  
**IMAGE PROCESSING DEVICE, IMAGE PROCESSING METHOD AND PROGRAM**

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, **SONY CORPORATION, a Japanese corporation, with offices at 1-7-1 Konan, Minato-ku, Tokyo, Japan** (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: \_\_\_\_\_, Filing Date: \_\_\_\_\_.

This assignment executed on the dates indicated below.

AYAKO IWASE \_\_\_\_\_

Name of first or sole inventor  
KANAGAWA JAPAN \_\_\_\_\_

Residence of first or sole inventor

*Ayako Iwase*  
Signature of first or sole inventor \_\_\_\_\_

*14th May 2010*  
Execution date of U.S. Patent Application \_\_\_\_\_

*14th May 2010*  
Date of this assignment \_\_\_\_\_

YUJI SAITOU \_\_\_\_\_

Name of second inventor  
TOKYO JAPAN \_\_\_\_\_

Residence of second inventor

Signature of second inventor \_\_\_\_\_

Execution date of U.S. Patent Application \_\_\_\_\_

Date of this assignment \_\_\_\_\_

NOBUKI FURUE \_\_\_\_\_

Name of third inventor  
TOKYO JAPAN \_\_\_\_\_

Residence of third inventor

Signature of third inventor \_\_\_\_\_

Execution date of U.S. Patent Application \_\_\_\_\_

Date of this assignment \_\_\_\_\_

**ADDITIONAL INVENTOR(S)**

SHINICHI IRIYA Name of fourth inventor KANAGAWA JAPAN Residence of fourth inventor Signature of fourth inventor	Execution date of U.S. Patent Application Date of this assignment
HIROYUKI OZAWA Name of fifth inventor TOKYO JAPAN Residence of fifth inventor Signature of fifth inventor	Execution date of U.S. Patent Application Date of this assignment
Name of sixth inventor Residence of sixth inventor Signature of sixth inventor	Execution date of U.S. Patent Application Date of this assignment
Name of seventh inventor Residence of seventh inventor Signature of seventh inventor	Execution date of U.S. Patent Application Date of this assignment
Name of eighth inventor Residence of eighth inventor Signature of eighth inventor	Execution date of U.S. Patent Application Date of this assignment
Name of ninth inventor Residence of ninth inventor Signature of ninth inventor	Execution date of U.S. Patent Application Date of this assignment

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**IMAGE PROCESSING DEVICE, IMAGE PROCESSING METHOD AND PROGRAM**

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NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

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This assignment executed on the dates indicated below.

AYAKO IWASE

\_\_\_\_\_  
Name of first or sole inventor  
KANAGAWA JAPAN  
\_\_\_\_\_  
Residence of First or sole inventor

\_\_\_\_\_  
Execution date of U.S. Patent Application

\_\_\_\_\_  
Signature of first or sole inventor

\_\_\_\_\_  
Date of this assignment

YUJI SAITOU

\_\_\_\_\_  
Name of second inventor  
TOKYO JAPAN  
\_\_\_\_\_  
Residence of second inventor

\_\_\_\_\_  
*May 7, 2010*  
Execution date of U.S. Patent Application

\_\_\_\_\_  
*Yuji Saitou*  
Signature of second inventor

\_\_\_\_\_  
*May 7, 2010*  
Date of this assignment

NOBUKI FURUE

\_\_\_\_\_  
Name of third inventor  
TOKYO JAPAN  
\_\_\_\_\_  
Residence of third inventor

\_\_\_\_\_  
Execution date of U.S. Patent Application

\_\_\_\_\_  
*Nobuki Furue*  
Signature of third inventor

\_\_\_\_\_  
*May 10, 2010*  
Date of this assignment

**ADDITIONAL INVENTOR(S)**

SHINICHI IRIYA Name of fourth inventor KANAGAWA JAPAN Residence of fourth inventor <i>Shinichi Iriya</i> Signature of fourth inventor	<u>May 29, 2010</u> Execution date of U.S. Patent Application <u>May 29, 2010</u> Date of this assignment
HIROYUKI OZAWA Name of fifth inventor TOKYO JAPAN Residence of fifth inventor <i>Hiroyuki Ozawa</i> Signature of fifth inventor	<u>May 31, 2010</u> Execution date of U.S. Patent Application <u>May 31, 2010</u> Date of this assignment
_____ Name of sixth inventor	_____ Execution date of U.S. Patent Application
_____ Residence of sixth inventor	_____
_____ Signature of sixth inventor	_____ Date of this assignment
_____ Name of seventh inventor	_____ Execution date of U.S. Patent Application
_____ Residence of seventh inventor	_____
_____ Signature of seventh inventor	_____ Date of this assignment
_____ Name of eighth inventor	_____ Execution date of U.S. Patent Application
_____ Residence of eighth inventor	_____
_____ Signature of eighth inventor	_____ Date of this assignment
_____ Name of ninth inventor	_____ Execution date of U.S. Patent Application
_____ Residence of ninth inventor	_____
_____ Signature of ninth inventor	_____ Date of this assignment